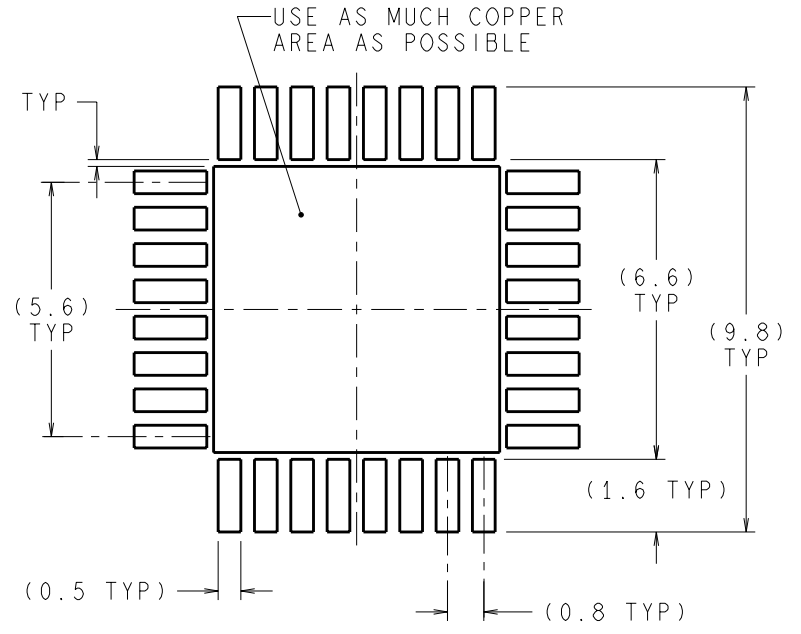
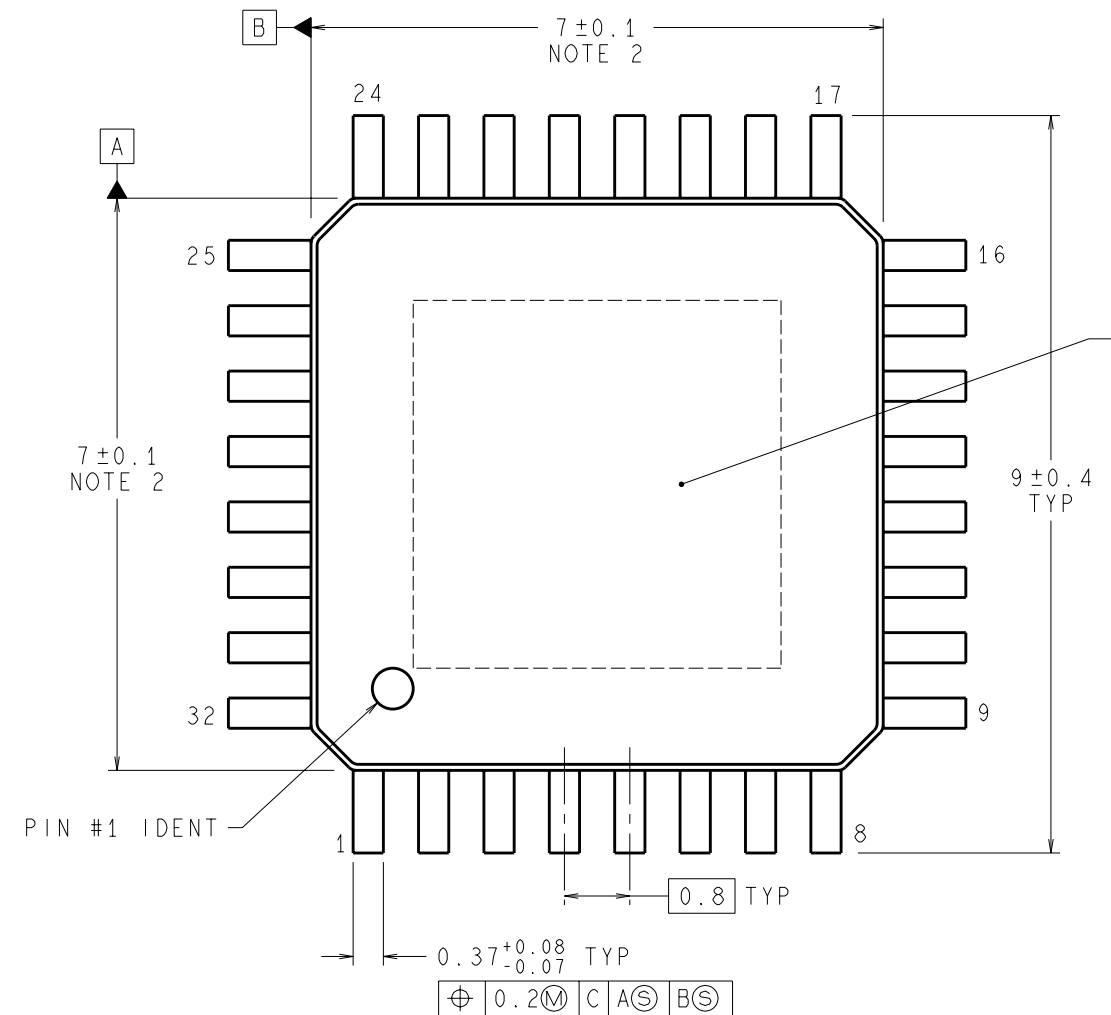
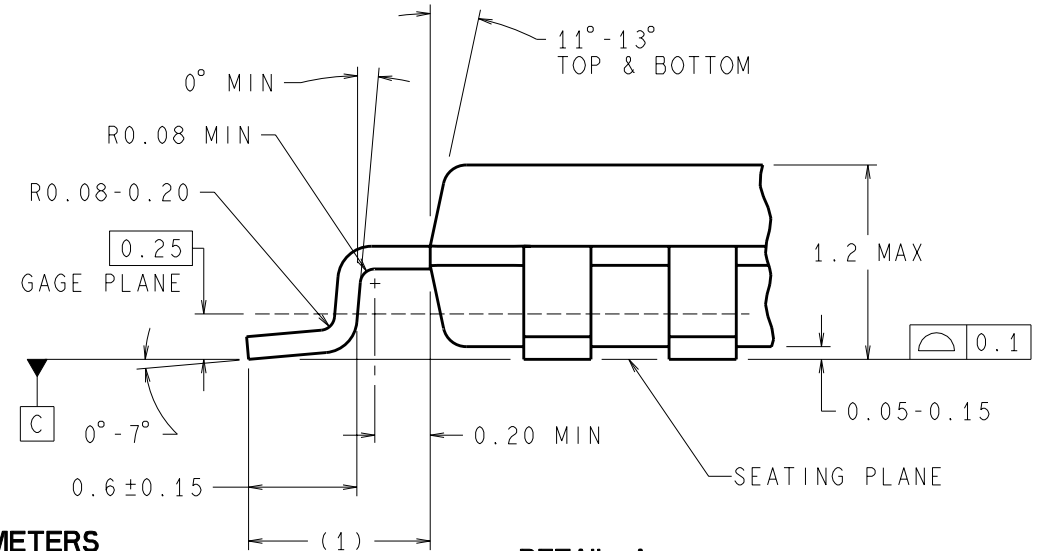
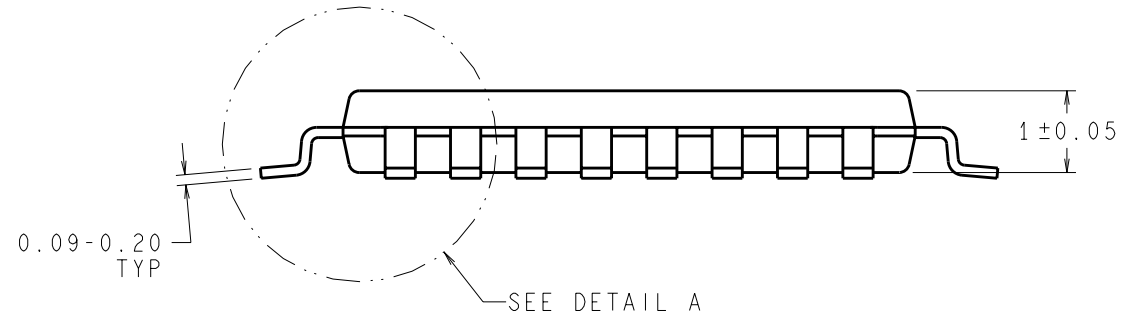


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12376	02/29/2000	TL/RW



LAND PATTERN RECOMMENDATION



DETAIL A
TYP, SCALE: 40X

DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH: 7.62 MICROMETERS MINIMUM SOLDER PLATING (85/15) THICKNESS ON COPPER.
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. MAXIMUM ALLOWABLE MOLD PROTRUSION 0.15mm PER SIDE.
- REFERENCE JEDEC REGISTRATION MS-026, VARIATION ABA, DATED FEBRUARY 1999.

APPROVALS		DATE		National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DRAWN T. LEQUANG		02/29/2000			
DFTG. CHK. MARTA SUCHY		02/29/2000			
ENGR. CHK. RANDY WALBERG		02/29/2000		TOFP, JEDEC METRIC, 7 X 7 X 1mm, EXPOSED PAD, 32 LEAD	
		SCALE N/A	SIZE C		
FORMERLY: N/A		SHEET 1 of 1			